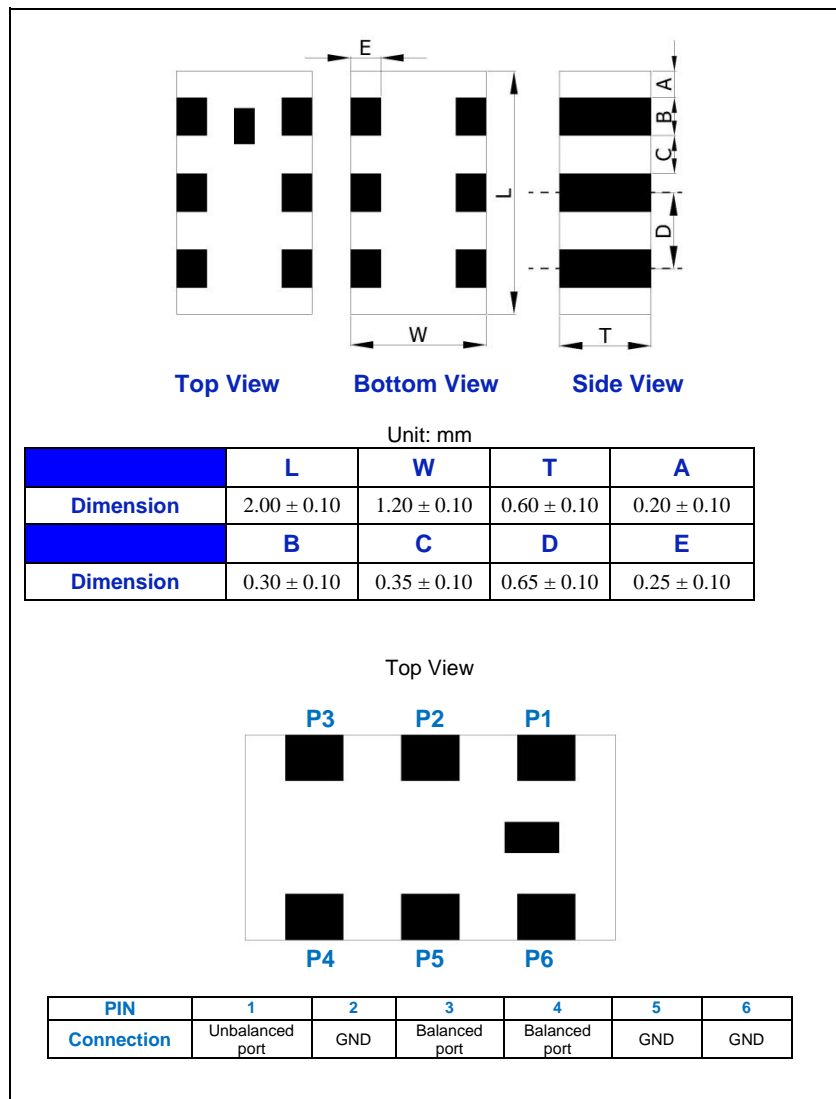


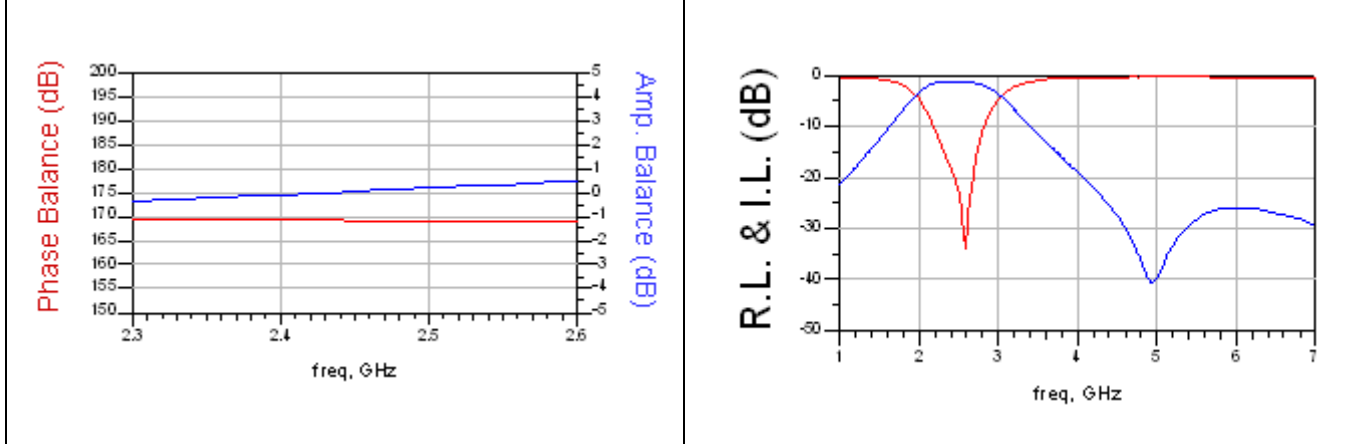
ELECTRICAL SPECIFICATION

SPECIFICATIONS		SPECIFICATIONS	UNIT
Frequency Range		2450 ± 50	MHz
Insertion Loss, Max		1.5	dB
Return Loss, minimum		10	dB
Unbalance Impedance		50	Ω
Balance Impedance		Match to TI2530 and 2531 Chipsets	-
Phase Difference		180° ± 15°	
Amplitude Difference, Max		2.0	dB
Attenuation, min	4800 ~ 5000 MHz	15	dB
	7200 ~ 7500 MHz	20	dB
Operating Temperature Range		-40 ~ +85	°C

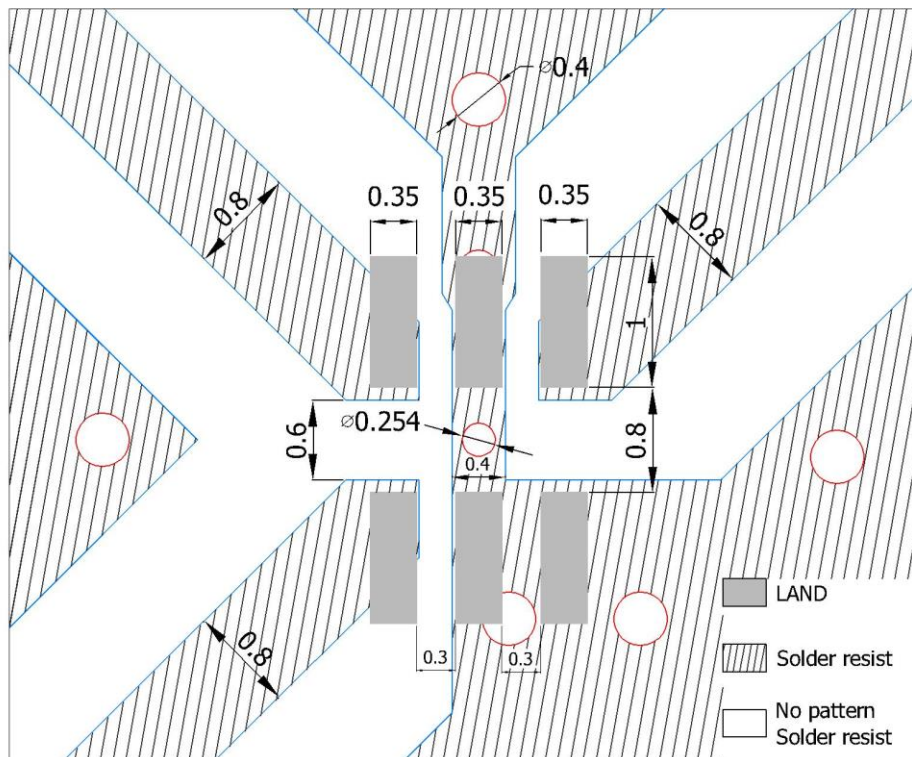
MECHANICAL SPECIFICATION



Typical Electrical Performance



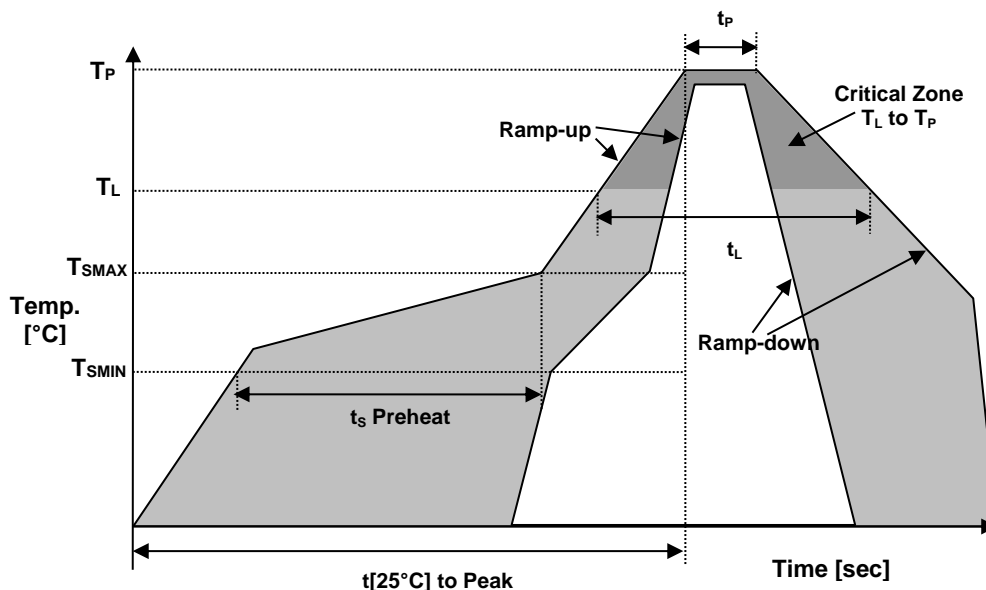
Solder Land Pattern



Unit : mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

REFLOW PROFILE



Reflow profile		
Temperature Min Preheat	T_{SMIN}	150°C
Temperature Max Preheat	T_{SMAX}	200°C
Time (T_{SMIN} to T_{SMAX})	t_s	60-180 sec.
Temperature	T_L	217°C
Peak Temperature	T_P	260°C
Ramp-up rate	R_{UP}	3°C/sec max.
Ramp-down rate	R_{DOWN}	6°C/sec max.
Time within 5°C of Peak Temperature	t_p	10 sec.
Time $t_{[25^\circ\text{C}]}$ to Peak Temperature	$t_{[25^\circ\text{C}]}$ to Peak	480 sec.
Time	t_L	60-150 sec.

ENVIRONMENTAL

PARAMETER	VALUE
MOISTURE SENSITIVITY LEVEL	1
RoHS2	6/6 COMPLIANT & LEAD FREE
REACH-SVHC	COMPLIANT
HALOGEN-FREE	COMPLIANT
TERMINATION FINISH	Sn



March, 2017